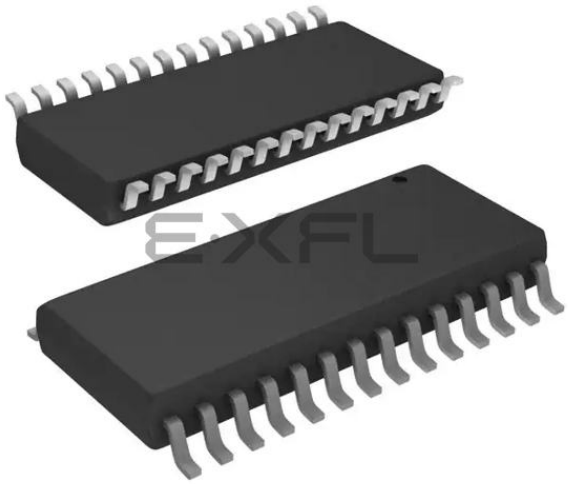

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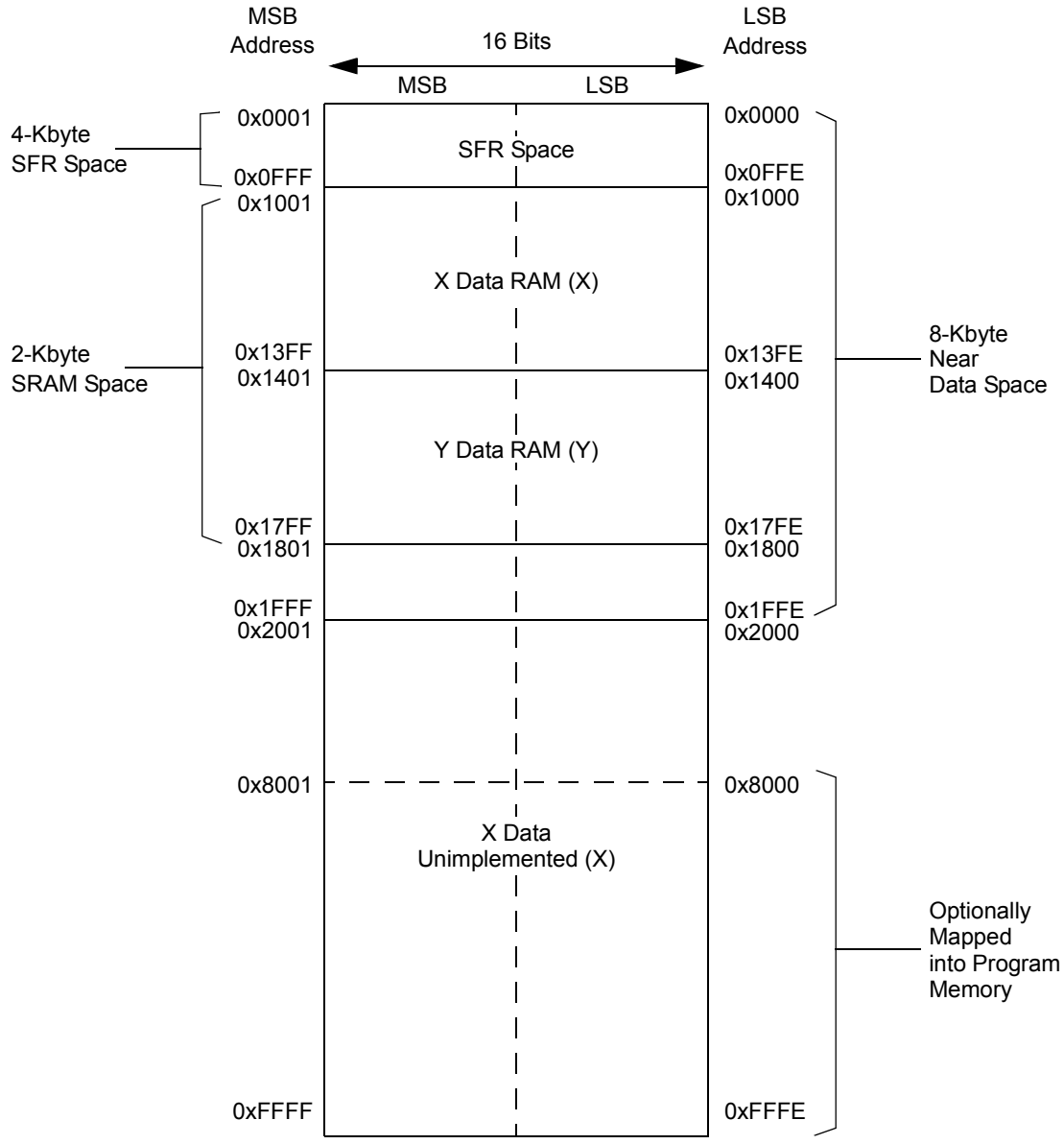
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	dsPIC
Core Size	16-Bit
Speed	60 MIPs
Connectivity	I²C, IrDA, LINbus, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	21
Program Memory Size	64KB (64K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	8K x 8
Voltage - Supply (Vcc/Vdd)	3V ~ 3.6V
Data Converters	A/D 12x12b; D/A 1x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	28-SOIC (0.295", 7.50mm Width)
Supplier Device Package	28-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/dspic33ep64gs502-e-so

FIGURE 4-6: DATA MEMORY MAP FOR dsPIC33EP16GS50X DEVICES



Note: Memory areas are not shown to scale.

TABLE 4-16: ADC REGISTER MAP (CONTINUED)

SFR Name	Addr.	Bit 15	Bit 14	Bit 13	Bit 12	Bit 11	Bit 10	Bit 9	Bit 8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	All Resets
ADLVLTRGL	03D0	LVLEN15(1)	LVLEN14	LVLEN13(1)	LVLEN12(2)	LVLEN11(2)	LVLEN10(2)	LVLEN9(2)	LVLEN8(2)	LVLEN7	LVLEN6	LVLEN5	LVLEN4	LVLEN3	LVLEN2	LVLEN1	LVLEN0	0000
ADLVLTRGH	03D2	—	—	—	—	—	—	—	—	—	—	LVLEN21	LVLEN20	LVLEN19	LVLEN18	LVLEN17(2)	LVLEN16(1)	0000
ADCORE0L	03D4	—	—	—	—	—	—	SAMC<9:0>										0000
ADCORE0H	03D6	—	—	—	EISEL2	EISEL1	EISEL0	RES1	RES0	—	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADCORE1L	03D8	—	—	—	—	—	—	SAMC<9:0>										0000
ADCORE1H	03DA	—	—	—	EISEL2	EISEL1	EISEL0	RES1	RES0	—	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADCORE2L	03DC	—	—	—	—	—	—	SAMC<9:0>										0000
ADCORE2H	03DE	—	—	—	EISEL2	EISEL1	EISEL0	RES1	RES0	—	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADCORE3L	03E0	—	—	—	—	—	—	SAMC<9:0>										0000
ADCORE3H	03E2	—	—	—	EISEL2	EISEL1	EISEL0	RES1	RES0	—	ADCS6	ADCS5	ADCS4	ADCS3	ADCS2	ADCS1	ADCS0	0000
ADEIEL	03F0	EIEN15(1)	EIEN14(2)	EIEN13(1)	EIEN12(2)	EIEN11(2)	EIEN10(2)	EIEN9(2)	EIEN8(2)	EIEN7	EIEN6	EIEN5	EIEN4	EIEN3	EIEN2	EIEN1	EIEN0	0000
ADEIEH	03F2	—	—	—	—	—	—	—	—	—	—	EIEN21	EIEN20	EIEN19	EIEN18	EIEN17(2)	EIEN16(1)	0000
ADEISTATL	03F8	EISTAT15(1)	EISTAT14(2)	EISTAT13(1)	EISTAT12(2)	EISTAT11(2)	EISTAT10(2)	EISTAT9(2)	EISTAT8(2)	EISTAT7	EISTAT6	EISTAT5	EISTAT4	EISTAT3	EISTAT2	EISTAT1	EISTAT0	0000
ADEISTATH	03FA	—	—	—	—	—	—	—	—	—	—	EISTAT21	EISTAT20	EISTAT19	EISTAT18	EISTAT17(2)	EISTAT16(1)	0000
ADCON5L	0400	SHRRDY	—	—	—	C3RDY	C2RDY	C1RDY	C0RDY	SHRPWR	—	—	—	C3PWR	C2PWR	C1PWR	C0PWR	0000
ADCON5H	0402	—	—	—	—	WARMTIME3	WARMTIME2	WARMTIME1	WARMTIME0	SHRCIE	—	—	—	C3CIE	C2CIE	C1CIE	C0CIE	0000
ADCAL0L	0404	CAL1RDY	—	—	—	—	CAL1DIFF	CAL1EN	CAL1RUN	CAL0RDY	—	—	—	—	CAL0DIFF	CAL0EN	CAL0RUN	0000
ADCAL0H	0406	CAL3RDY	—	—	—	—	CAL3DIFF	CAL3EN	CAL3RUN	CAL2RDY	—	—	—	—	CAL2DIFF	CAL2EN	CAL2RUN	0000
ADCAL1H	040A	CSHRRDY	—	—	—	—	CSHRDIFF	CSHREN	CSHRRUN	—	—	—	—	—	—	—	—	0000
ADCBUF0	040C	ADC Data Buffer 0																0000
ADCBUF1	040E	ADC Data Buffer 1																0000
ADCBUF2	0410	ADC Data Buffer 2																0000
ADCBUF3	0412	ADC Data Buffer 3																0000
ADCBUF4	0414	ADC Data Buffer 4																0000
ADCBUF5	0416	ADC Data Buffer 5																0000
ADCBUF6	041B	ADC Data Buffer 6																0000
ADCBUF7	041A	ADC Data Buffer 7																0000
ADCBUF8	041C	ADC Data Buffer 8																0000
ADCBUF9	041E	ADC Data Buffer 9																0000
ADCBUF10	0420	ADC Data Buffer 10																0000
ADCBUF11	0422	ADC Data Buffer 11																0000
ADCBUF12	0424	ADC Data Buffer 12																0000
ADCBUF13	0426	ADC Data Buffer 13																0000
ADCBUF14	0428	ADC Data Buffer 14																0000
ADCBUF15	042A	ADC Data Buffer 15																0000
ADCBUF16	042C	ADC Data Buffer 16																0000
ADCBUF17	042E	ADC Data Buffer 17																0000
ADCBUF18	0430	ADC Data Buffer 18																0000
ADCBUF19	0432	ADC Data Buffer 19																0000
ADCBUF20	0434	ADC Data Buffer 20																0000
ADCBUF21	0436	ADC Data Buffer 21																0000

Legend: — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Implemented on dsPIC33EPXXGS506 devices only.

2: Implemented on dsPIC33EPXXGS504/505 and dsPIC33EPXXGS506 devices only.

4.5.1 PAGED MEMORY SCHEME

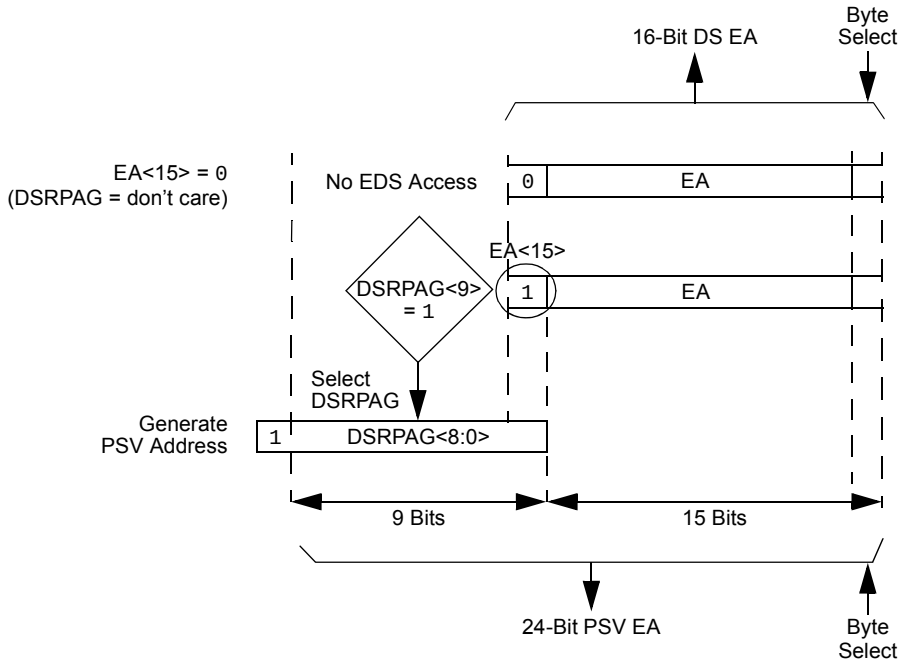
The dsPIC33EPXXGS50X architecture extends the available Data Space through a paging scheme, which allows the available Data Space to be accessed using MOV instructions in a linear fashion for pre- and post-modified Effective Addresses (EAs). The upper half of the base Data Space address is used in conjunction with the Data Space Page (DSRPAG) register to form the Program Space Visibility (PSV) address.

The Data Space Page (DSRPAG) register is located in the SFR space. Construction of the PSV address is shown in Figure 4-9. When DSRPAG<9> = 1 and the base address bit, EA<15> = 1, the DSRPAG<8:0> bits are concatenated onto EA<14:0> to form the 24-bit PSV read address.

The paged memory scheme provides access to multiple 32-Kbyte windows in the PSV memory. The Data Space Page (DSRPAG) register, in combination with the upper half of the Data Space address, can provide up to 8 Mbytes of PSV address space. The paged data memory space is shown in Figure 4-10.

The Program Space (PS) can be accessed with a DSRPAG of 0x200 or greater. Only reads from PS are supported using the DSRPAG.

FIGURE 4-9: PROGRAM SPACE VISIBILITY (PSV) READ ADDRESS GENERATION



Note: DS read access when DSRPAG = 0x000 will force an address error trap.

4.7 Modulo Addressing

Modulo Addressing mode is a method of providing an automated means to support circular data buffers using hardware. The objective is to remove the need for software to perform data address boundary checks when executing tightly looped code, as is typical in many DSP algorithms.

Modulo Addressing can operate in either Data or Program Space (since the Data Pointer mechanism is essentially the same for both). One circular buffer can be supported in each of the X (which also provides the pointers into Program Space) and Y Data Spaces. Modulo Addressing can operate on any W Register Pointer. However, it is not advisable to use W14 or W15 for Modulo Addressing since these two registers are used as the Stack Frame Pointer and Stack Pointer, respectively.

In general, any particular circular buffer can be configured to operate in only one direction, as there are certain restrictions on the buffer start address (for incrementing buffers) or end address (for decrementing buffers), based upon the direction of the buffer.

The only exception to the usage restrictions is for buffers that have a power-of-two length. As these buffers satisfy the start and end address criteria, they can operate in a Bidirectional mode (that is, address boundary checks are performed on both the lower and upper address boundaries).

4.7.1 START AND END ADDRESS

The Modulo Addressing scheme requires that a starting and ending address be specified and loaded into the 16-bit Modulo Buffer Address registers: XMODSRT, XMODEND, YMODSRT and YMODEND (see Table 4-2).

Note:	Y space Modulo Addressing EA calculations assume word-sized data (LSb of every EA is always clear).

The length of a circular buffer is not directly specified. It is determined by the difference between the corresponding start and end addresses. The maximum possible length of the circular buffer is 32K words (64 Kbytes).

4.7.2 W ADDRESS REGISTER SELECTION

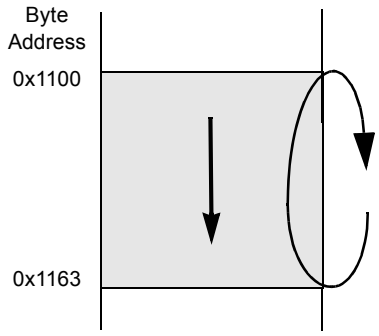
The Modulo and Bit-Reversed Addressing Control register, MODCON<15:0>, contains enable flags, as well as a W register field to specify the W Address registers. The XWM and YWM fields select the registers that operate with Modulo Addressing:

- If XWM = 1111, X RAGU and X WAGU Modulo Addressing is disabled
- If YWM = 1111, Y AGU Modulo Addressing is disabled

The X Address Space Pointer W (XWM) register, to which Modulo Addressing is to be applied, is stored in MODCON<3:0> (see Table 4-2). Modulo Addressing is enabled for X Data Space when XWM is set to any value other than '1111' and the XMODEN bit is set (MODCON<15>).

The Y Address Space Pointer W (YWM) register, to which Modulo Addressing is to be applied, is stored in MODCON<7:4>. Modulo Addressing is enabled for Y Data Space when YWM is set to any value other than '1111' and the YMODEN bit (MODCON<14>) is set.

FIGURE 4-12: MODULO ADDRESSING OPERATION EXAMPLE




```
MOV     #0x1100, W0
MOV     W0, XMODSRT     ;set modulo start address
MOV     #0x1163, W0
MOV     W0, MODEND      ;set modulo end address
MOV     #0x8001, W0
MOV     W0, MODCON      ;enable W1, X AGU for modulo

MOV     #0x0000, W0     ;W0 holds buffer fill value

MOV     #0x1110, W1     ;point W1 to buffer

DO      AGAIN, #0x31    ;fill the 50 buffer locations
MOV     W0, [W1++]      ;fill the next location
AGAIN:  INC W0, W0      ;increment the fill value
```

REGISTER 7-7: INTTREG: INTERRUPT CONTROL AND STATUS REGISTER

U-0	U-0	U-0	U-0	R-0	R-0	R-0	R-0
—	—	—	—	ILR3	ILR2	ILR1	ILR0
bit 15							bit 8

R-0	R-0	R-0	R-0	R-0	R-0	R-0	R-0
VECNUM7	VECNUM6	VECNUM5	VECNUM4	VECNUM3	VECNUM2	VECNUM1	VECNUM0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as ‘0’

bit 11-8 **ILR<3:0>:** New CPU Interrupt Priority Level bits
1111 = CPU Interrupt Priority Level is 15
•
•
•
0001 = CPU Interrupt Priority Level is 1
0000 = CPU Interrupt Priority Level is 0

bit 7-0 **VECNUM<7:0>:** Vector Number of Pending Interrupt bits
11111111 = 255, Reserved; do not use
•
•
•
00001001 = 9, IC1 – Input Capture 1
00001000 = 8, INT0 – External Interrupt 0
00000111 = 7, Reserved; do not use
00000110 = 6, Generic soft error trap
00000101 = 5, Reserved; do not use
00000100 = 4, Math error trap
00000011 = 3, Stack error trap
00000010 = 2, Generic hard trap
00000001 = 1, Address error trap
00000000 = 0, Oscillator fail trap

9.0 POWER-SAVING FEATURES

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"Watchdog Timer and Power-Saving Modes"** (DS70615) in the "*dsPIC33/PIC24 Family Reference Manual*", which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The dsPIC33EPXXGS50X family devices provide the ability to manage power consumption by selectively managing clocking to the CPU and the peripherals. In general, a lower clock frequency and a reduction in the number of peripherals being clocked constitutes lower consumed power.

dsPIC33EPXXGS50X family devices can manage power consumption in four ways:

- Clock Frequency
- Instruction-Based Sleep and Idle modes
- Software-Controlled Doze mode
- Selective Peripheral Control in Software

Combinations of these methods can be used to selectively tailor an application's power consumption while still maintaining critical application features, such as timing-sensitive communications.

9.1 Clock Frequency and Clock Switching

The dsPIC33EPXXGS50X family devices allow a wide range of clock frequencies to be selected under application control. If the system clock configuration is not locked, users can choose low-power or high-precision oscillators by simply changing the NOSCx bits (OSCCON<10:8>). The process of changing a system clock during operation, as well as limitations to the process, are discussed in more detail in **Section 8.0 "Oscillator Configuration"**.

9.2 Instruction-Based Power-Saving Modes

The dsPIC33EPXXGS50X family devices have two special power-saving modes that are entered through the execution of a special PWRSAV instruction. Sleep mode stops clock operation and halts all code execution. Idle mode halts the CPU and code execution, but allows peripheral modules to continue operation. The assembler syntax of the PWRSAV instruction is shown in Example 9-1.

Note: SLEEP_MODE and IDLE_MODE are constants defined in the assembler include file for the selected device.

Sleep and Idle modes can be exited as a result of an enabled interrupt, WDT time-out or a device Reset. When the device exits these modes, it is said to "wake-up".

EXAMPLE 9-1: PWRSAV INSTRUCTION SYNTAX

```
PWRSAV  #SLEEP_MODE    ; Put the device into Sleep mode
PWRSAV  #IDLE_MODE     ; Put the device into Idle mode
```

REGISTER 9-2: PMD2: PERIPHERAL MODULE DISABLE CONTROL REGISTER 2

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	IC4MD	IC3MD	IC2MD	IC1MD
bit 15							bit 8

U-0	U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	—	OC4MD	OC3MD	OC2MD	OC1MD
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-12 **Unimplemented:** Read as '0'

bit 11 **IC4MD:** Input Capture 4 Module Disable bit
1 = Input Capture 4 module is disabled
0 = Input Capture 4 module is enabled

bit 10 **IC3MD:** Input Capture 3 Module Disable bit
1 = Input Capture 3 module is disabled
0 = Input Capture 3 module is enabled

bit 9 **IC2MD:** Input Capture 2 Module Disable bit
1 = Input Capture 2 module is disabled
0 = Input Capture 2 module is enabled

bit 8 **IC1MD:** Input Capture 1 Module Disable bit
1 = Input Capture 1 module is disabled
0 = Input Capture 1 module is enabled

bit 7-4 **Unimplemented:** Read as '0'

bit 3 **OC4MD:** Output Compare 4 Module Disable bit
1 = Output Compare 4 module is disabled
0 = Output Compare 4 module is enabled

bit 2 **OC3MD:** Output Compare 3 Module Disable bit
1 = Output Compare 3 module is disabled
0 = Output Compare 3 module is enabled

bit 1 **OC2MD:** Output Compare 2 Module Disable bit
1 = Output Compare 2 module is disabled
0 = Output Compare 2 module is enabled

bit 0 **OC1MD:** Output Compare 1 Module Disable bit
1 = Output Compare 1 module is disabled
0 = Output Compare 1 module is enabled

TABLE 10-2: OUTPUT SELECTION FOR REMAPPABLE PINS (RPn)

Function	RPnR<5:0>	Output Name
Default PORT	000000	RPn tied to Default Pin
U1TX	000001	RPn tied to UART1 Transmit
$\overline{U1RTS}$	000010	RPn tied to UART1 Request-to-Send
U2TX	000011	RPn tied to UART2 Transmit
$\overline{U2RTS}$	000100	RPn tied to UART2 Request-to-Send
SDO1	000101	RPn tied to SPI1 Data Output
SCK1	000110	RPn tied to SPI1 Clock Output
$\overline{SS1}$	000111	RPn tied to SPI1 Slave Select
SDO2	001000	RPn tied to SPI2 Data Output
SCK2	001001	RPn tied to SPI2 Clock Output
$\overline{SS2}$	001010	RPn tied to SPI2 Slave Select
OC1	010000	RPn tied to Output Compare 1 Output
OC2	010001	RPn tied to Output Compare 2 Output
OC3	010010	RPn tied to Output Compare 3 Output
OC4	010011	RPn tied to Output Compare 4 Output
ACMP1	011000	RPn tied to Analog Comparator 1 Output
ACMP2	011001	RPn tied to Analog Comparator 2 Output
ACMP3	011010	RPn tied to Analog Comparator 3 Output
SYNCO1	101101	RPn tied to PWM Primary Master Time Base Sync Output
SYNCO2	101110	RPn tied to PWM Secondary Master Time Base Sync Output
REFCLKO	110001	RPn tied to Reference Clock Output
ACMP4	110010	RPn tied to Analog Comparator 4 Output
PWM4H	110011	RPn tied to PWM Output Pins Associated with PWM Generator 4
PWM4L	110100	RPn tied to PWM Output Pins Associated with PWM Generator 4
PWM5H	110101	RPn tied to PWM Output Pins Associated with PWM Generator 5
PWM5L	110110	RPn tied to PWM Output Pins Associated with PWM Generator 5

REGISTER 10-8: RPINR12: PERIPHERAL PIN SELECT INPUT REGISTER 12

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLT2R7	FLT2R6	FLT2R5	FLT2R4	FLT2R3	FLT2R2	FLT2R1	FLT2R0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLT1R7	FLT1R6	FLT1R5	FLT1R4	FLT1R3	FLT1R2	FLT1R1	FLT1R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **FLT2R<7:0>:** Assign PWM Fault 2 (FLT2) to the Corresponding RPn Pin bits

10110101 = Input tied to RP181
10110100 = Input tied to RP180
•
•
•
00000001 = Input tied to RP1
00000000 = Input tied to Vss

bit 7-0 **FLT1R<7:0>:** Assign PWM Fault 1 (FLT1) to the Corresponding RPn Pin bits

10110101 = Input tied to RP181
10110100 = Input tied to RP180
•
•
•
00000001 = Input tied to RP1
00000000 = Input tied to Vss

REGISTER 10-19: RPINR43: PERIPHERAL PIN SELECT INPUT REGISTER 43

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLT8R7	FLT8R6	FLT8R5	FLT8R4	FLT8R3	FLT8R2	FLT8R1	FLT8R0
bit 15							bit 8

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
FLT7R7	FLT7R6	FLT7R5	FLT7R4	FLT7R3	FLT7R2	FLT7R1	FLT7R0
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as ‘0’	
-n = Value at POR	‘1’ = Bit is set	‘0’ = Bit is cleared	x = Bit is unknown

bit 15-8 **FLT8R<7:0>:** Assign PWM Fault 8 (FLT8) to the Corresponding RPn Pin bits

10110101 = Input tied to RP181
10110100 = Input tied to RP180
•
•
•
00000001 = Input tied to RP1
00000000 = Input tied to Vss

bit 7-0 **FLT7R<7:0>:** Assign PWM Fault 7 (FLT7) to the Corresponding RPn Pin bits

10110101 = Input tied to RP181
10110100 = Input tied to RP180
•
•
•
00000001 = Input tied to RP1
00000000 = Input tied to Vss

REGISTER 19-26: ADTRIGxL: ADC CHANNEL TRIGGER x SELECTION REGISTER LOW (x = 0 to 5)

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	TRGSRC(4x+1)<4:0>				
bit 15							bit 8

U-0	U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
—	—	—	TRGSRC(4x)<4:0>				
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit, read as '0'	
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 15-13 **Unimplemented:** Read as '0'

bit 12-8 **TRGSRC(4x+1)<4:0>:** Trigger Source Selection for Corresponding Analog Inputs bits

11111 = ADTRG31
11110 = Reserved
11101 = Reserved
11100 = PWM Generator 5 current-limit trigger
11011 = PWM Generator 4 current-limit trigger
11010 = PWM Generator 3 current-limit trigger
11001 = PWM Generator 2 current-limit trigger
11000 = PWM Generator 1 current-limit trigger
10111 = Output Compare 2 trigger
10110 = Output Compare 1 trigger
10101 = Reserved
10100 = Reserved
10011 = PWM Generator 5 secondary trigger
10010 = PWM Generator 4 secondary trigger
10001 = PWM Generator 3 secondary trigger
10000 = PWM Generator 2 secondary trigger
01111 = PWM Generator 1 secondary trigger
01110 = PWM secondary Special Event Trigger
01101 = Timer2 period match
01100 = Timer1 period match
01011 = Reserved
01010 = Reserved
01001 = PWM Generator 5 primary trigger
01000 = PWM Generator 4 primary trigger
00111 = PWM Generator 3 primary trigger
00110 = PWM Generator 2 primary trigger
00101 = PWM Generator 1 primary trigger
00100 = PWM Special Event Trigger
00011 = Reserved
00010 = Level software trigger
00001 = Common software trigger
00000 = No trigger is enabled

bit 7-5 **Unimplemented:** Read as '0'

20.0 HIGH-SPEED ANALOG COMPARATOR

Note 1: This data sheet summarizes the features of the dsPIC33EPXXGS50X family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **"High-Speed Analog Comparator Module"** (DS70005128) in the *"dsPIC33/PIC24 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com).

2: Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The high-speed analog comparator module monitors current and/or voltage transients that may be too fast for the CPU and ADC to capture.

20.1 Features Overview

The SMPS comparator module offers the following major features:

- Four Rail-to-Rail Analog Comparators
- Dedicated 12-Bit DAC for each Analog Comparator
- Up to Six Selectable Input Sources per Comparator:
  - Four external inputs
  - Two internal inputs from the PGAx module
- Programmable Comparator Hysteresis
- Programmable Output Polarity
- Up to Two DAC Outputs to Device Pins
- Multiple Voltage References for the DAC:
  - External References (EXTREF1 or EXTREF2)
  - AV_{DD}
- Interrupt Generation Capability
- Functional Support for PWMx:
  - PWMx duty cycle control
  - PWMx period control
  - PWMx Fault detected

TABLE 23-2: CONFIGURATION BITS DESCRIPTION

Bit Field	Description
BSS<1:0>	Boot Segment Code-Protect Level bits 11 = Boot Segment is not code-protected other than BWRP 10 = Standard security 0x = High security
BSEN	Boot Segment Control bit 1 = No Boot Segment is enabled 0 = Boot Segment size is determined by the BSLIM<12:0> bits
BWRP	Boot Segment Write-Protect bit 1 = Boot Segment can be written 0 = Boot Segment is write-protected
BSLIM<12:0>	Boot Segment Flash Page Address Limit bits Contains the last active Boot Segment page. The value to be programmed is the inverted page address, such that programming additional '0's can only increase the Boot Segment size (i.e., 0x1FFD = 2 Pages or 1024 IW).
GSS<1:0>	General Segment Code-Protect Level bits 11 = User program memory is not code-protected 10 = Standard security 0x = High security
GWRP	General Segment Write-Protect bit 1 = User program memory is not write-protected 0 = User program memory is write-protected
CWRP	Configuration Segment Write-Protect bit 1 = Configuration data is not write-protected 0 = Configuration data is write-protected
CSS<2:0>	Configuration Segment Code-Protect Level bits 111 = Configuration data is not code-protected 110 = Standard security 10x = Enhanced security 0xx = High security
BTSWP	BOOTSWP Instruction Enable/Disable bit 1 = BOOTSWP instruction is disabled 0 = BOOTSWP instruction is enabled
BSEQ<11:0>	Boot Sequence Number bits (Dual Partition modes only) Relative value defining which partition will be active after device Reset; the partition containing a lower boot number will be active.
IBSEQ<11:0>	Inverse Boot Sequence Number bits (Dual Partition modes only) The one's complement of BSEQ<11:0>; must be calculated by the user and written for device programming. If BSEQx and IBSEQx are not complements of each other, the Boot Sequence Number is considered to be invalid.
AIVTDIS(1)	Alternate Interrupt Vector Table bit 1 = Alternate Interrupt Vector Table is disabled 0 = Alternate Interrupt Vector Table is enabled if INTCON2<8> = 1
IESO	Two-Speed Oscillator Start-up Enable bit 1 = Starts up device with FRC, then automatically switches to the user-selected oscillator source when ready 0 = Starts up device with the user-selected oscillator source
PWMLOCK	PWMx Lock Enable bit 1 = Certain PWMx registers may only be written after a key sequence 0 = PWMx registers may be written without a key sequence

Note 1: The Boot Segment must be present to use the Alternate Interrupt Vector Table.

FIGURE 26-17: SPIx SLAVE MODE (FULL-DUPLEX, CKE = 0, CKP = 1, SMP = 0) TIMING CHARACTERISTICS

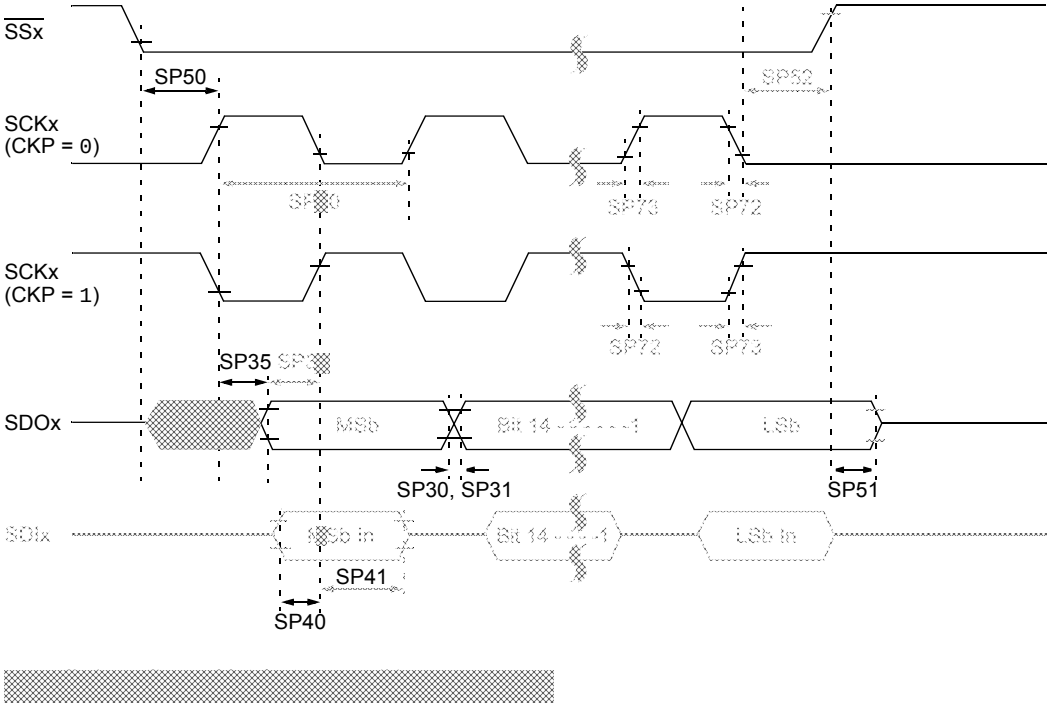


TABLE 26-44: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS(2)			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristics**	**Min.**	**Typ.(1)**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	ADC Clock Period	14.28	—	—	ns	
Throughput Rate							
AD51	FTP	SH0-SH3	—	—	3.25	Msps	70 MHz ADC clock, 12 bits, no pending conversion at time of trigger
		SH4	—	—	3.25	Msps	

Note 1: These parameters are characterized but not tested in manufacturing.

2: The ADC module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is ensured, but not characterized.

TABLE 26-45: HIGH-SPEED ANALOG COMPARATOR MODULE SPECIFICATIONS

AC/DC CHARACTERISTICS(2)			Standard Operating Conditions: 3.0V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +125°C for Extended				
Param No.	**Symbol**	**Characteristic**	**Min.**	**Typ.**	**Max.**	**Units**	**Comments**
CM10	VIOFF	Input Offset Voltage	-35	±5	+35	mV	
CM11	VICM	Input Common-Mode Voltage Range(1)	0	—	AVDD	V	
CM13	CMRR	Common-Mode Rejection Ratio	60	—	—	dB	
CM14	TRESP	Large Signal Response	—	15	—	ns	V+ input step of 100 mV while V- input is held at AVDD/2. Delay measured from analog input pin to PWMx output pin.
CM15	VHYST	Input Hysteresis	5	10	20	mV	Depends on HYSSEL<1:0>
CM16	TON	Comparator Enabled to Valid Output	—	—	1	µs	

Note 1: These parameters are for design guidance only and are not tested in manufacturing.

2: The comparator module is functional at VBORMIN < VDD < VDDMIN, but with degraded performance. Unless otherwise stated, module functionality is tested, but not characterized.

27.0 DC AND AC DEVICE CHARACTERISTICS GRAPHS

Note: The graphs provided following this note are a statistical summary based on a limited number of samples and are provided for design guidance purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore, outside the warranted range.

FIGURE 27-1: VOH – 4x DRIVER PINS

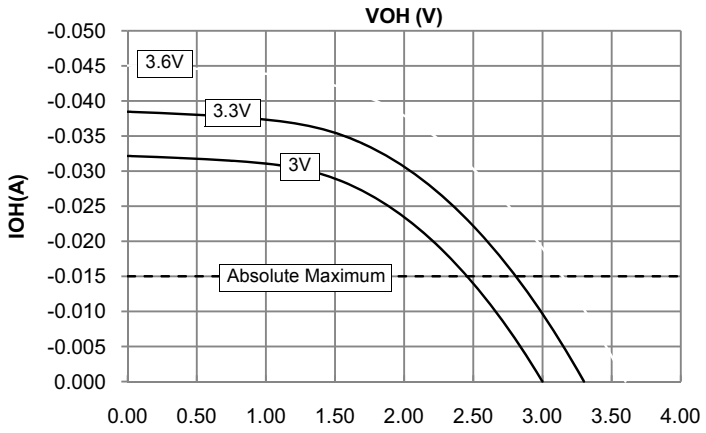


FIGURE 27-2: VOH – 8x DRIVER PINS

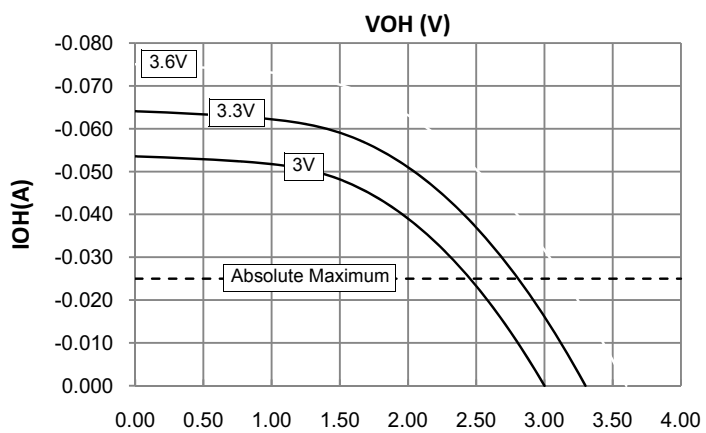


FIGURE 27-3: VOL – 4x DRIVER PINS

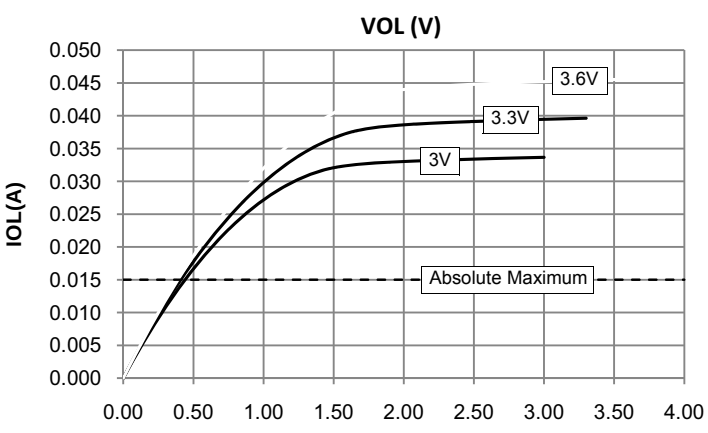


FIGURE 27-4: VOL – 8x DRIVER PINS

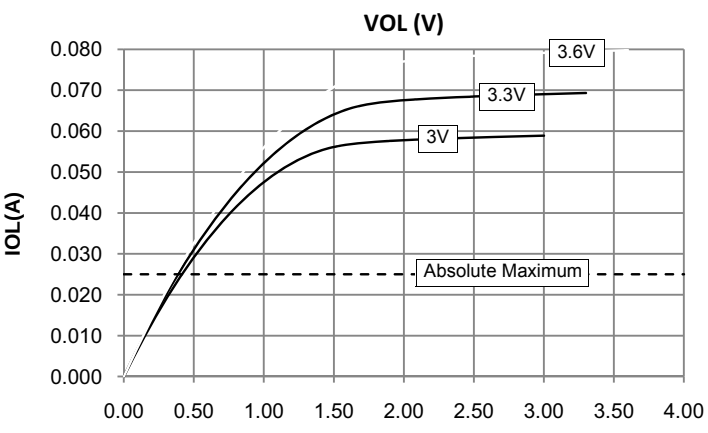


FIGURE 27-5: TYPICAL IPD CURRENT @ VDD = 3.3V

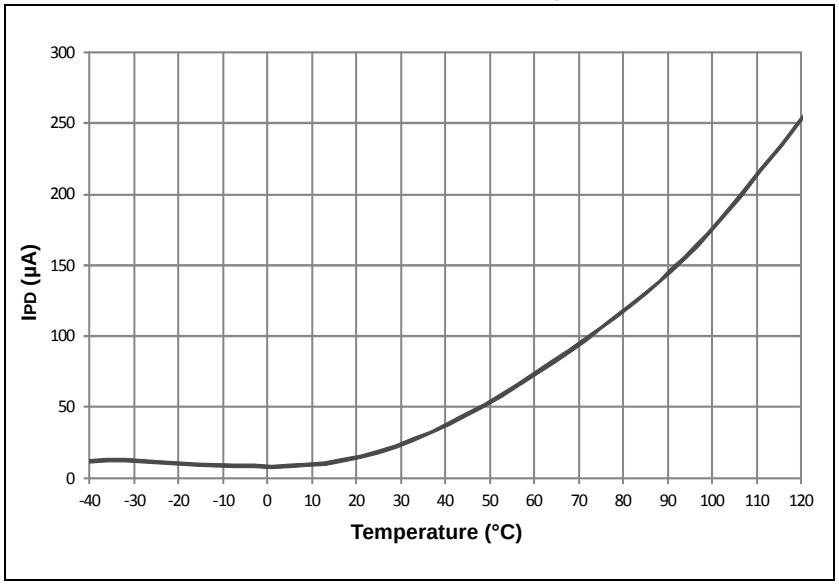


FIGURE 27-6: TYPICAL IDD CURRENT @ VDD = 3.3V, +25°C

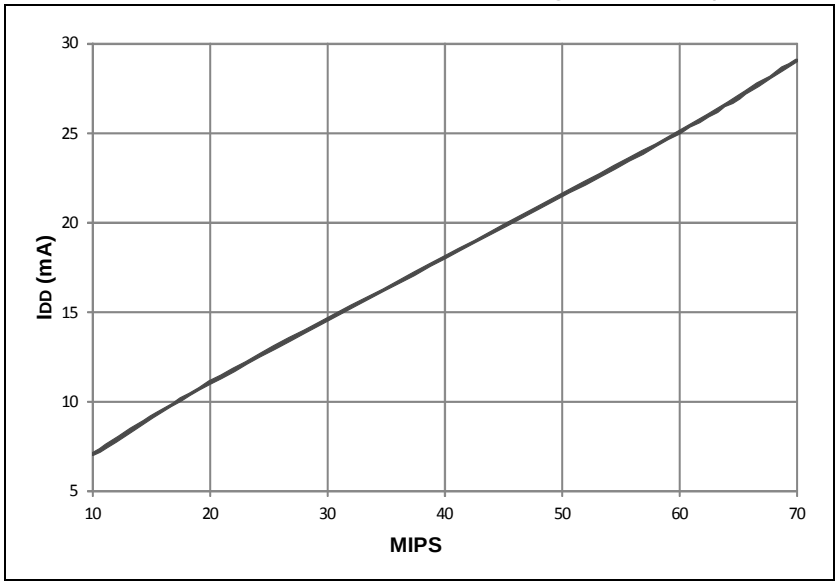


FIGURE 27-7: TYPICAL IDOZE CURRENT @ VDD = 3.3V, +25°C

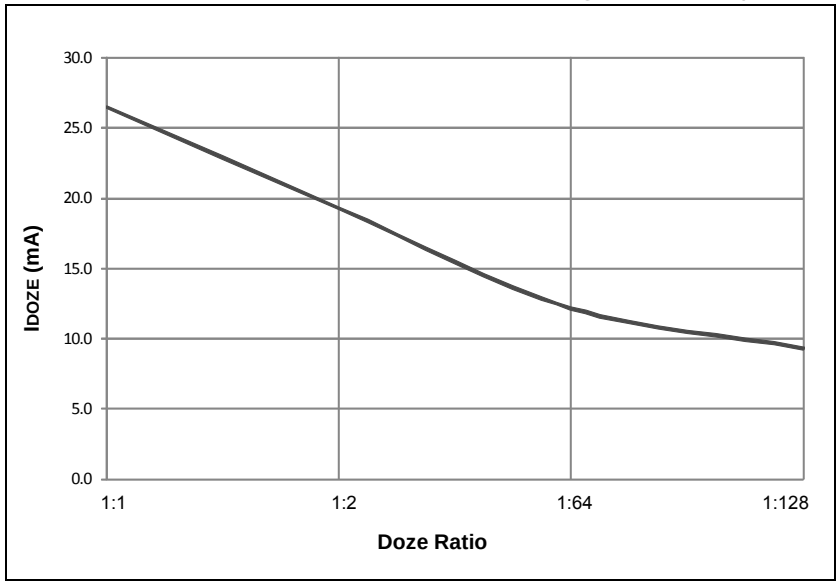
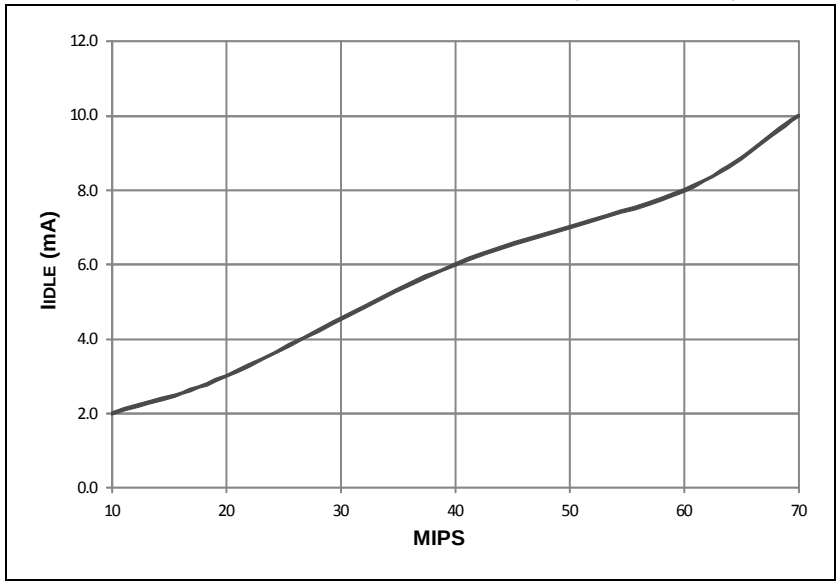


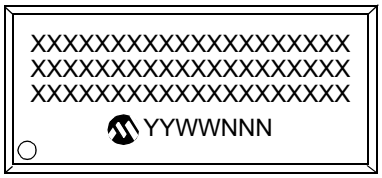
FIGURE 27-8: TYPICAL IIDLE CURRENT @ VDD = 3.3V, +25°C



28.0 PACKAGING INFORMATION

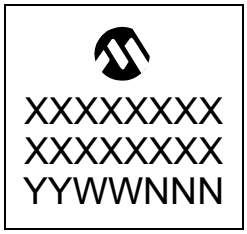
28.1 Package Marking Information

28-Lead SOIC (.300”)



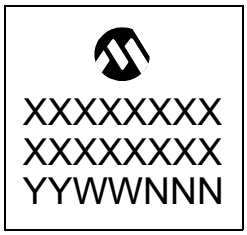
Example

28-Lead UQFN (6x6x0.55 mm)



Example

28-Lead QFN-S (6x6x0.9 mm)



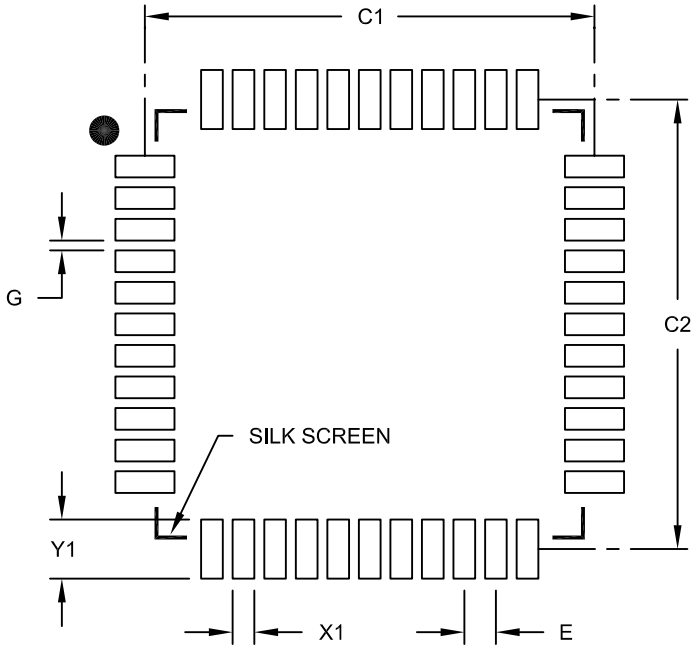
Example

Legend:	XX...X	Customer-specific information
	Y	Year code (last digit of calendar year)
	YY	Year code (last 2 digits of calendar year)
	WW	Week code (week of January 1 is week ‘01’)
	NNN	Alphanumeric traceability code

Note: In the event the full Microchip part number cannot be marked on one line, it will be carried over to the next line, thus limiting the number of available characters for customer-specific information.

44-Lead Plastic Thin Quad Flatpack (PT) 10X10X1 mm Body, 2.00 mm Footprint [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Contact Pitch	E	0.80 BSC		
Contact Pad Spacing	C1		11.40	
Contact Pad Spacing	C2		11.40	
Contact Pad Width (X44)	X1			0.55
Contact Pad Length (X44)	Y1			1.50
Distance Between Pads	G	0.25		

Notes:

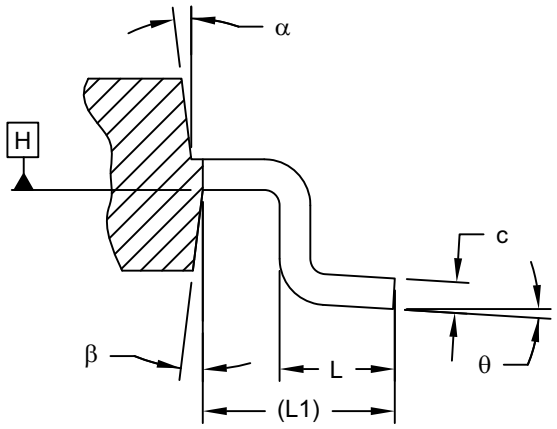
1. Dimensioning and tolerancing per ASME Y14.5M

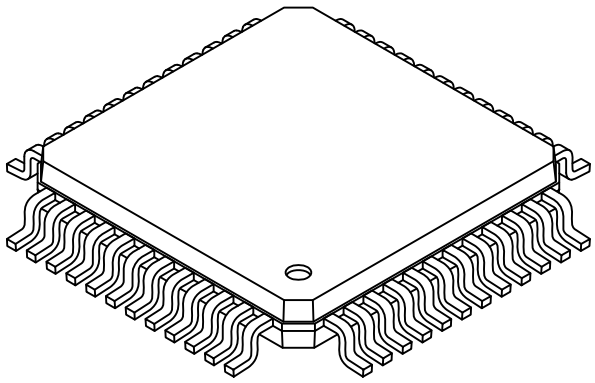
BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2076B

48-Lead Thin Quad Flatpack (Y8) - 7x7x1.0 mm Body [TQFP]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





SECTION A-A

Units		MILLIMETERS		
Dimension Limits		MIN	NOM	MAX
Number of Leads	N		48	
Lead Pitch	e		0.50 BSC	
Overall Height	A	-	-	1.20
Standoff	A1	0.05	-	0.15
Molded Package Thickness	A2	0.95	1.00	1.05
Foot Length	L	0.45	0.60	0.75
Footprint	L1		1.00 REF	
Foot Angle	ϕ	0°	3.5°	7°
Overall Width	E		9.00 BSC	
Overall Length	D		9.00 BSC	
Molded Package Width	E1		7.00 BSC	
Molded Package Length	D1		7.00 BSC	
Lead Thickness	c	0.09	-	0.16
Lead Width	b	0.17	0.22	0.27
Mold Draft Angle Top	α	11°	12°	13°
Mold Draft Angle Bottom	β	11°	12°	13°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Chamfers at corners are optional; size may vary.
3. Dimensions D1 and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.25mm per side.
4. Dimensioning and tolerancing per ASME Y14.5M

   BSC: Basic Dimension. Theoretically exact value shown without tolerances.

   REF: Reference Dimension, usually without tolerance, for information purposes only.
5. Datums A-B and D to be determined at center line between leads where leads exit plastic body at datum plane H

Microchip Technology Drawing C04-300-Y8 Rev A Sheet 2 of 2